

MA756

Silicon epitaxial planer type (cathode common)

For switching power supply

■ Features

- Forward current (average) $I_{F(AV)}$: 10A type
- Repetitive peak reverse voltage V_{RRM} : 60V type
- Sealed in TO-220F full-pack package, with high reliability
- Cathode common dual type
- Low forward voltage V_F

■ Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	60	V
Average forward current	$I_{F(AV)}$	10	A
Non-repetitive peak forward surge current	I_{FSM}^*	120	A
Junction temperature	T_j	- 40 to +125	°C
Storage temperature	T_{stg}	- 40 to +125	°C

* Sine half wave : 10ms/cycle

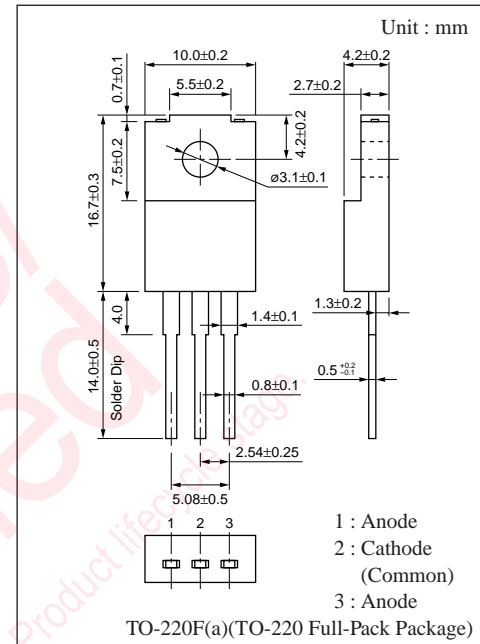
■ Electrical Characteristics (Ta= 25°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	I_R	$V_R = 60V$			3	mA
Forward voltage (DC)	V_F	$I_F = 5A$			0.58	V
Thermal resistance	$R_{th(j-c)}$	Flat direct current between junction and case			3	°C/W

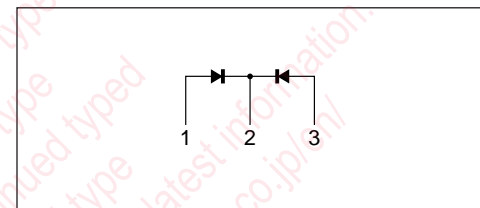
❖ Rated input/output frequency : 150MHz

■ Marking

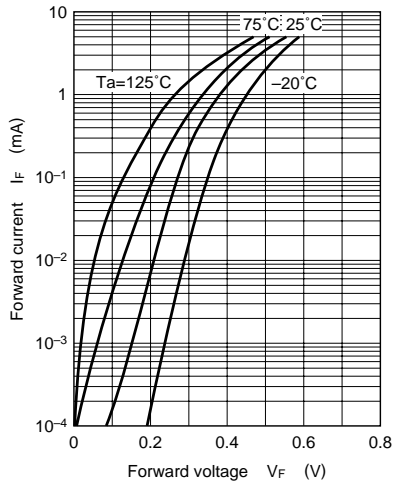
Part Number	MA756
Symbol	MA756



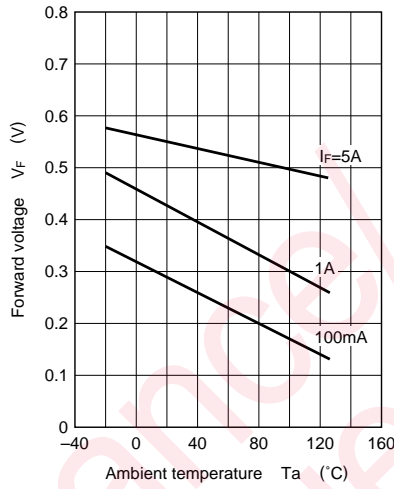
■ Internal Connection



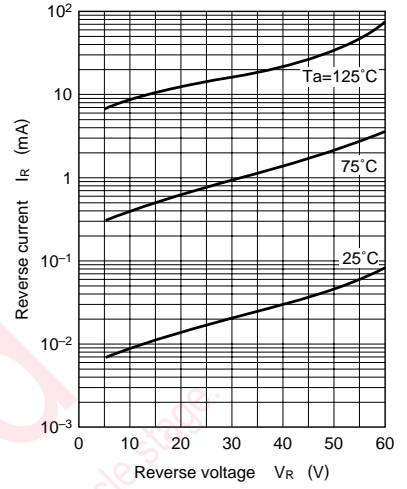
$I_F - V_F$



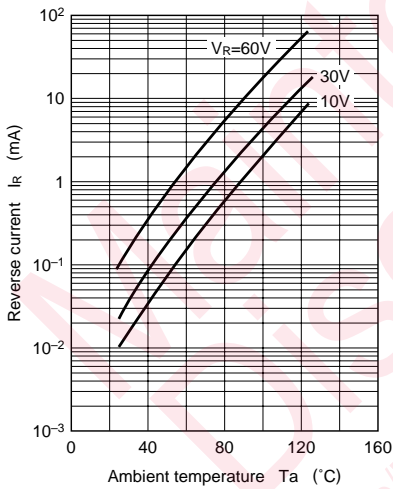
$V_F - T_a$



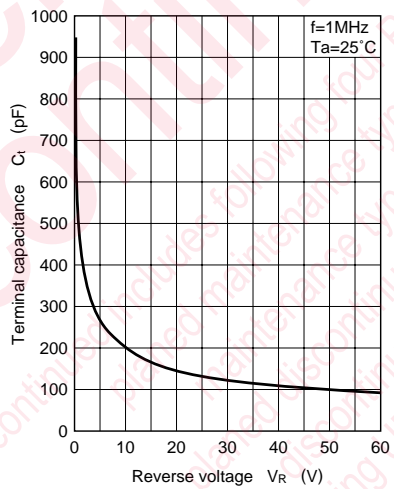
$I_R - V_R$



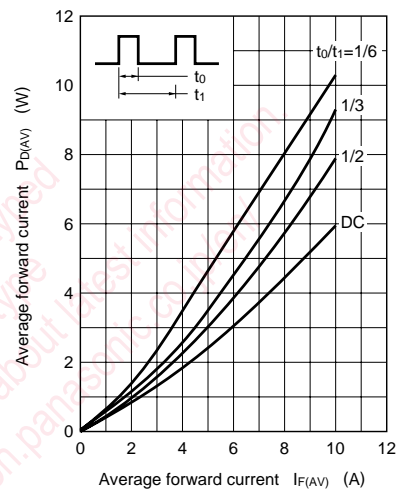
$I_R - T_a$



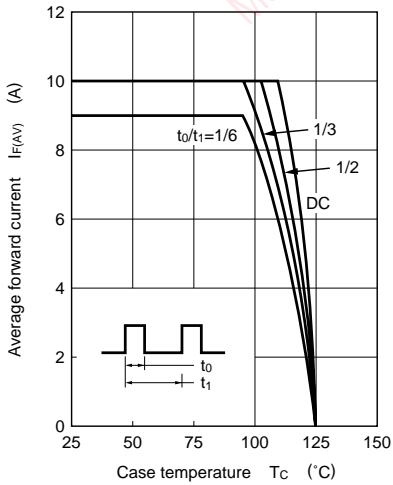
$C_t - V_R$



$P_{D(AV)} - I_{F(AV)}$



$I_{F(AV)} - T_C$



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